

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/19/11663	
1.3 Title of PCN	XDLF AMKOR: new and additional TSSOP8 assembly & test line for CMOSF8H+ Industrial Range EEPROM	
1.4 Product Category	EEPROM (industrial range) from CMOSF8H+ process in TSSOP8	
1.5 Issue date	2019-07-09	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Benoit RODRIGUES
2.1.2 Marketing Manager	Hubert LEDUC
2.1.3 Quality Manager	Rita PAVANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Machines	New equipment changing process technique or using different technology(eg first equipment of a new brand)	Amkor (Philippines)

4. Description of change

	Old	New
4.1 Description	The EEPROM products (industrial range) processed with CMOSF8H+ process technology at ST Rousset (France) are assembled/tested in TSSOP8 package at ST Shenzhen (China).	The EEPROM products (industrial range) processed with CMOSF8H+ process technology will be also assembled/tested on new AMKOR extra high density lead frame (XDLF) assembly line.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Form: Marking change - Fit: No change - Function: No change	

5. Reason / motivation for change

5.1 Motivation	The strategy of STMicroelectronics Memory Division is to support our customers on a long-term basis. In line with this commitment, the qualification of the AMKOR new XDLF TSSOP8 assembly line for the EEPROM products (industrial range) in CMOSF8H+ will increase the production capacity throughput and consequently improve the service to our customers.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	The difference is visible inside the Trace Code PYWW where the first digit P for Assembly plant is "B" for AMKOR, this digit being "K" for current ST Shenzhen assembly plant.
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7. Timing / schedule

7.1 Date of qualification results	2019-07-19
7.2 Intended start of delivery	2019-10-01
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	
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8.2 Qualification report and qualification results	In progress	Issue Date	
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9. Attachments (additional documentations)
11663 Public product.pdf 11663 PCN AMKOR XDLF TSSOP F8H+.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24128-BRDW6TP	
	M24128-BWDW6TP	
	M24C01-RDW6TP	
	M24C01-WDW6TP	
	M24C02-FDW6TP	
	M24C02-RDW6TP	
	M24C02-WDW6TP	
	M24C04-FDW6TP	
	M24C04-RDW6TP	
	M24C04-WDW6TP	
	M24C08-FDW6TP	
	M24C08-RDW6TP	
	M24C08-WDW6TP	
	M24C16-FDW6TP	
	M24C16-RDW6TP	
	M24C16-WDW6TP	
	M24C32-FDW6TP	
	M24C32-RDW6TP	
	M24C32-WDW6TP	
	M24C64-FDW6TP	
	M24C64-RDW6TP	
	M24C64-WDW6TP	
	M34E02-FDW6TP	

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Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : XDLF AMKOR: new and additional TSSOP8 assembly & test line for CMOSF8H+ Industrial Range EEPROM

PCN Reference : MDG/19/11663

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

M24C08-WDW6TP	M24C08-RDW6TP	M24C01-RDW6TP
M24C02-FDW6TP	M24C64-RDW6TP	M24C04-WDW6TP
M24C64-FDW6TP	M24C02-WDW6TP	M24C16-RDW6TP
M24C64-WDW6TP	M24C08-FDW6TP	M24C02-RDW6TP
M24128-BRDW6TP	M24C01-WDW6TP	M24C16-FDW6TP
M24C32-WDW6TP	M24C32-FDW6TP	M24128-BWDW6TP
M24C04-FDW6TP	M24C32-RDW6TP	M24C16-WDW6TP
M24C04-RDW6TP	M34E02-FDW6TP	



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